

IBIS Chair's Report

Lance Wang

Zuken USA

Chair, IBIS Open Forum

DesignCon 2025 IBIS Summit

Santa Clara, CA, USA

January 31, 2025

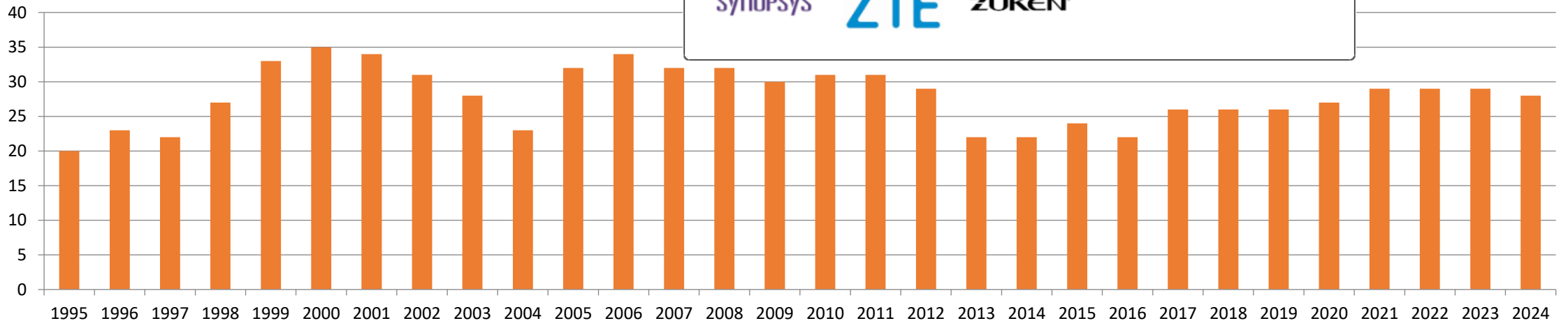


An SAE Industry Technologies Consortia Program

28 IBIS Members (Organization-based)



Number of Members by Year



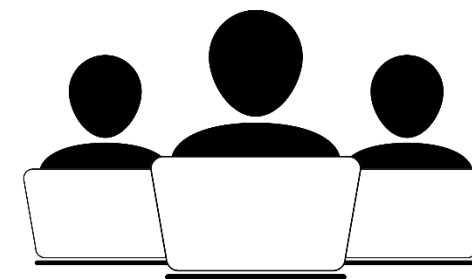
IBIS Officers June 2024- May 2025



Chair: *Lance Wang, Zuken USA*
Vice-Chair: *Doug Burns, SI-Clarity*
Secretary: *Graham Kus, MathWorks*
Treasurer: *Randy Wolff, Siemens EDA*
Librarian: *Zhiping Yang, PCB Automation & MST*
Postmaster: *Curtis Clark, Ansys*
Webmaster: *Steve Parker, Marvell*

- University Relations: *Chulsoon Hwang, MST*
- IEEE DASC IBIS Liaison: *Michael Mirmak, Intel*

Elected



Appointed

Website Updates



Summits Registration

- [Summits Home](#)
- [Summit List](#)
- [Thank You](#)

Summit Online Registration

Upload IBIS Open Forum Minutes Form:

[IBIS Open Forum - Upload Open Forum Minutes](#)

Upload File

Meeting date:

File format:

File name: No file chosen

IBIS Open Forum Meeting Minutes

Upcoming Events
Past Summits

Open Forum
Minutes
Task Groups
ATM
Quality
Interconnect
Editorial

Members
Roster

Specifications
BIRDS
Models

Support
Model Review
FREE Tools
IBIS Parsers
IBISCHK
IBISCHK Bugs
TSCHK
TSCHK Bugs
IBIS Cookbook
Accuracy Handbook
IBIS Quality Spec

Site Map
About IBIS
Articles
FAQ

Meeting Date	Filename	Format
2024-11-22	m112224.docx	docx
2024-11-22	m112224.pdf	pdf

Meeting Date	Filename	Format
2024-11-01	m110124.docx	docx
2024-11-01	m110124.pdf	pdf
2024-10-04	m100424.docx	docx
2024-10-04	m100424.pdf	pdf
2024-09-13	m091324.docx	docx
2024-09-13	m091324.pdf	pdf
2024-08-23	m082324.docx	docx
2024-08-23	m082324.pdf	pdf
2024-08-09	m080924.docx	docx
2024-08-09	m080924.pdf	pdf
2024-07-12	m071224.docx	docx
2024-07-12	m071224.pdf	pdf
2024-06-21	m062124.docx	docx
2024-06-21	m062124.pdf	pdf
2024-05-31	m053124.docx	docx
2024-05-31	m053124.pdf	pdf
2024-05-15	m051524.docx	docx
2024-05-15	m051524.pdf	pdf
2024-05-10	m051024.docx	docx
2024-05-10	m051024.pdf	pdf
2024-04-19	m041924.pdf	pdf

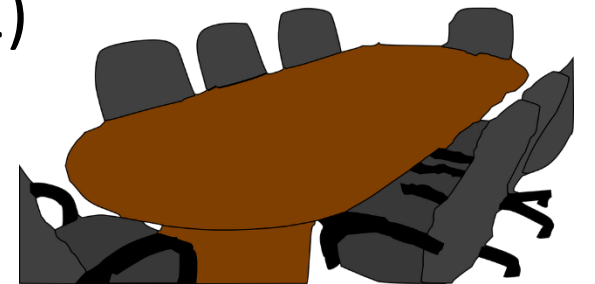
Hosted on: app.ibis.org

Hosted on: ibis.org

IBIS Meetings



- Weekly teleconferences
 - Quality task group (Tuesdays, 09:00 PT)
 - Advanced Technology Modeling (ATM) task group (Tuesdays, 12:00 PT)
 - Interconnect task group (Wednesdays, 08:00 PT)
 - Editorial task group (Fridays, 8:00 PT when no IBIS OF meeting)
- IBIS Open Forum teleconference every 3 weeks (Fridays, 08:00 PT)
- IBIS Summit meetings (USA and international)
 - DesignCon, IEEE SPI, IEEE EMC+SIPI, Shanghai, Tokyo (JEITA-organized)
- Participants: ~330 in 2024 (~290 in 2023, ~280 in 2022)



SAE ITC



- SAE Industry Technologies Consortia is the parent organization of the IBIS Open Forum
- IBIS is assisted by SAE employees Tammy Patton, Richard DeMary, and Peter Doty
- SAE ITC provides financial, legal, and other services
- <https://www.sae-itc.com/>



2025 IBIS Membership Dues



- IBIS Open Forum needs more income due to increased SAE ITC management fees for 2025
 - 2025 SAE ITC fee is ~\$39,000
 - Members have voted to approve a dues increase for 2025
 - Income from IBISCHK8 parser sales (and expected increase to parser license fee) should close the revenue gap
- 2025 dues are based on company size, with discounted rate for educational institutions:
 - Small company (<50 employees) = \$750
 - Large company (50+ employees) = \$1,400
 - Education institution = \$500

Task Groups



- Advanced Technology Modeling Task Group
 - Chair: Arpad Muranyi, Siemens EDA
 - https://ibis.org/atm_wip/
 - Develop non-interconnect technical BIRDS
- Editorial Task Group
 - Chair: Michael Mirmak, Intel
 - https://ibis.org/editorial_wip/
 - Produce IBIS specification documents
- Interconnect Task Group
 - Chair: Michael Mirmak, Intel
 - https://ibis.org/interconn_wip/
 - Develop on-die/package/module/connector interconnect modeling BIRDS
- Quality Task Group
 - Acting Chair: Randy Wolff, Siemens EDA
 - https://ibis.org/quality_wip/
 - Oversee IBISCHK parser testing and development



BIRD = Buffer Issue Resolution Document

IBIS Milestones



I/O Buffer Information Specification

Other Work

- 1993-1994 **IBIS 1.0-2.1:**
 - Behavioral buffer model (fast simulation)
 - Component pin map (easy EDA import)
- 1997-1999 **IBIS 3.0-3.2:**
 - Package models
 - Electrical Board Description (EBD)
- 2002-2006 **IBIS 4.0-4.2:**
 - Receiver models
 - AMS languages
- 2007-2012 **IBIS 5.0-5.1:**
 - IBIS-AMI SerDes models
 - Power-aware model
- 2013-2015 **IBIS 6.0-6.1:**
 - PAM4 multi-level signaling
 - Power delivery package models
- 2019 **IBIS 7.0:**
 - Back-channel time-domain support
 - Interconnect modeling using IBIS-ISS and Touchstone
- 2021 **IBIS 7.1:**
 - DDRx IBIS-AMI support
 - Electrical Module Description (EMD)
 - IBIS-AMI back-channel statistical optimization
- 2023 **IBIS 7.2:**
 - Redriver simulation flow fixes
 - PAMn IBIS-AMI support
- **2025 IBIS 8.0**
 - **In progress**
- 1995: **ANSI/EIA-656 (IBIS 2.1 International standard)**
- 1999: **ANSI/EIA-656-A (IBIS 3.2 International standard)**
- 2001: **IEC 62014-1 (IBIS 3.2 International standard)**
- 2003: **Interconnect Model Specification (ICM 1.0)**
- 2006: **ANSI/EIA-656-B (IBIS 4.2 International standard)**
- 2009: **Touchstone 2.0**
 - Official Touchstone donated from Agilent/Keysight
- 2011: **IBIS-ISS 1.0 (Interconnect SPICE Subcircuit)**
 - Subset of HSPICE
- 2024: **Touchstone 2.1**
 - Clarify S-parameter Definition
 - [End] Keyword Corrections and Other Editorial Changes
 - Per Port Reference Resistance on the Option Line
 - Clarify File Extension Rule for Touchstone 1.0 and 1.1 Files
- **IBISCHK:** IBIS file syntax parser
 - Current version 7.2.1
 - Source code available for purchase
 - Compiled executables available free of charge
- **TSCHK2:** Touchstone 2.1 file syntax parser
 - Current version 2.1.0
 - Source code available for purchase
 - Compiled executables available free of charge

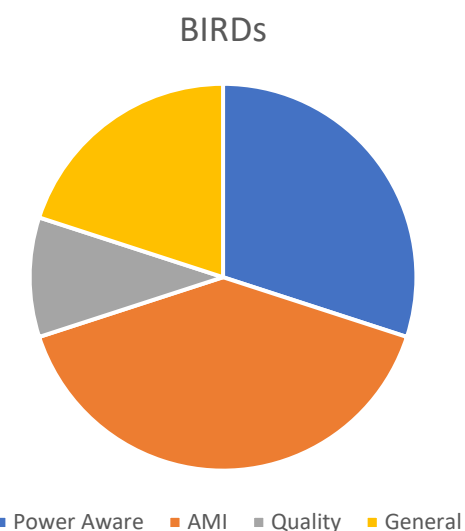
Planning for IBIS Version 8.0



Current official BIRD content

BIRD ID	BIRD Title	Approval Date	Note
223.1	Add support for SPIM in IBIS	November 17, 2023	Power Aware
224	New AMI Reserved Parameters for Ts4file port order	June 23, 2023	AMI
225	Clarification for bus_label rules	September 15, 2023	Power Aware
226	PSIJ Sensitivity	December 8, 2023	Power Aware
227	AMI Ignore Block Feature	January 5, 2024	AMI
228	Pin Name Field Extension	January 26, 2024	General
229.1	AMI Test Data Support	April 19, 2024	AMI, Quality
230.1	Adding a Definitions Section to IBIS	May 31, 2024	General
231	Clarifications on AMI Block Concepts	May 31, 2024	AMI

- Motions were approved on June 21, 2024
- Will fix many editorial issues in IBIS 7.2
 - [ver7_2_known_issues.docx](#)





Buffer Issue Resolution Documents (BIRD)

To submit a BIRD to the IBIS Open Forum, please use the [BIRD Template, Rev. 1.3](#).

ID#	Issue Title	Requester	Date Submitted	Date Accepted	Supporting Version
232	Clarification of Ts4file and Non-AMI Feature Relationships	Michael Mirmak, Intel Corporation	November 19, 2024		
231	Clarifications on AMI Block Concepts	Michael Mirmak, Intel Corporation	March 26, 2024	May 31, 2024	
230.1	Adding a Definitions Section to IBIS	Michael Mirmak, Intel Corporation	March 19, 2024; April 30, 2024	May 31, 2024	
229.1	AMI Test Data Support	Michael Mirmak, Intel Corp.	December 19, 2023, February 13, 2024	April 19, 2024	
228	Pin Name Field Extension	Michael Mirmak, Intel Corporation	December 5, 2023	January 26, 2024	
227	AMI Ignore Block Feature	Alaeddin A. Aydiner, Sai Zhou, Intel Corp.	November 14, 2023	January 5, 2024	
226	PSIJ Sensitivity	Kinger Cai, Fern Nee Tan, Chi-te Chen, Michael Mirmak, Intel Corp.	August 8, 2023	December 8, 2023	
225	Clarification for bus_label rules	Arpad Muranyi, Weston Beal, Randy Wolff, Siemens EDA	July 11, 2023	September 15, 2023	
224	New AMI Reserved Parameters for Ts4file port order	Liwei Zhao, Intel Corp.; Michael Mirmak, Intel Corp.	April 25, 2023	June 23, 2023	
223.1	Add support for SPIM in IBIS	Kinger Cai, Chi-te Chen, Intel Corp.	March 7, 2023, September 12, 2023	July 14, 2023 (223); November 17, 2023 (223.1)	
222	Clock Times Clarifications	Arpad Muranyi, Siemens EDA	November 8, 2022	December 9, 2022	7.2
221	AMI_parameters_in Clarification	Michael Mirmak, Intel Corp.	October 26, 2022	December 9, 2022	7.2
220.2	Pre-driver PSIJ Keyword	Yifan Ding, Chulsoon Hwang, Missouri S&T; Zhiping Yang, PCB Automation Inc., Missouri S&T; Arpad Muranyi, Randy Wolff, Siemens EDA	October 20, 2022, November 1, 2024, January 6, 2025		
219.1	AMI Parameter Root Name Clarifications	Michael Mirmak, Intel Corp.	March 29, 2022, May 3, 2022	August 12, 2022	7.2
218	Designator Pin List Relaxation	Arpad Muranyi, Siemens EDA	March 2, 2022	April 22, 2022	7.2
217	Require Clocked Rx Models to Return Clock Times	Arpad Muranyi, Siemens EDA	January 18, 2022	March 11, 2022	7.2
216	Alphanumeric Pin Names	Arpad Muranyi, Siemens EDA	January 18, 2022	March 11, 2022	7.2
215	Back-channel Statistical Optimization Editorial Update	Randy Wolff, Micron Technology; Bob Ross, Teraspeed Labs	September 22, 2021	October 29, 2021	7.1



Touchstone Issue Resolution Documents (TSIRD)

To submit an TSIRD to the IBIS Open Forum, please use the [TSIRD Template Rev. 1.0](#).

ID#	Issue Title	Requestor	Date Submitted	Date Accepted	Supported Version	Formats
8	Option line changes	Arpad Muranyi, Siemens EDA	March 20 2024	May 10 2024		(DOC)
7.2	Standardized Pole-Residue Representation of Touchstone Data	Arpad Muranyi, Siemens EDA	February 14, 2024; May 7, 2024; June 3, 2024	August 23, 2024		(DOC)
6	Clarify File Extension Rule for Touchstone 1.0 and 1.1 Files	Bob Ross, Teraspeed Labs; Arpad Muranyi, Siemens EDA	July 5, 2023	September 15, 2023	2.1	(DOC)
5.1	Per Port Reference Resistance on the Option Line	Arpad Muranyi, Randy Wolff, Siemens EDA; Bob Ross, Teraspeed Labs	June 14, 2023; July 5, 2023	September 15, 2023	2.1	(DOC)
4.1	[End] Keyword Corrections and Other Editorial Changes	Michael Mirmak, Intel Corp.	March 2, 2022 , July 20, 2022	September 9, 2022	2.1	(DOC)
3	Clarify S-parameter Definition	Radek Biernacki, Agilent Technologies; Michael Mirmak, Intel	July 20, 2011 ,	October 7, 2011	2.1	(DOC)
2.1	Binary Format Support	Michael Mirmak, Intel Corp. for Interconnect Task Group	June 9, 2010 , July 14, 2010	August 20, 2010		(DOC)
1.1	Sparse Matrix Mapping	Bob Ross, Teraspeed Consulting Group for Interconnect Task Group	February 26, 2010, April 23, 2010	April 23, 2010		(DOC)

The incorporation of the TSIRDs into versions of Touchstone are shown in [tsirdir.txt](#).

IBISCHK Development



- The latest parser 7.2.1 was delivered on December 21, 2023
- Covers 6 BUG fixes (BUG 239 and BUG 241-245)
 - <https://ibis.org/bugs/ibischk/>
- 6 more bugs found and classified after IBISCHK 7.2.1
- IBISCHK8 development contract is in progress

IBISCHK Parser Issue Reports (BUGs)

To find out how to submit a bug to the IBIS Open Forum, please read the document [bugform.txt](#).

ID#	Title	Requester	Date Submitted	Severity	Priority	Status	Date Closed	Supported Version
251	Missing Repeater_Type not seen through Model Selector	Arpad Muranyi, Siemens EDA	November 15, 2024	SEVERE	HIGH	OPEN		
250	Incorrect [Diff Pin] caution report	Michael Mirmak, Intel Corp.	July 1, 2024	ANNOYING	LOW	OPEN		
249	Memory leaks caused by algmod.c, ami.c and cmn.c	Michael Mirmak, Intel Corporation	March 28, 2024	ANNOYING	LOW	OPEN		
248	Crash Caused by iassert macro and abort()	Michael Mirmak, Intel Corporation	March 19, 2024	FATAL	MEDIUM	OPEN		
247	Changing BOOL from Type Enum to Int	Michael Mirmak, Intel Corporation	March 19, 2024	ENHANCEMENT	LOW	OPEN		
246	Clarification on Slash Characters and Parser Usage	Michael Mirmak, Intel Corporation	December 22, 2023	MODERATE	MEDIUM	OPEN		
245	Has Platform Issue Message in IBIS-AMI Checking Not Clear	Weston Beal, Siemens EDA	June 13, 2023	MODERATE	LOW	CLOSED	December 8, 2023	7.2.1
244	False IBIS Ver Compatibility Error for EMD and IBIS File Checking	Randy Wolff, Arpad Muranyi; Siemens EDA	June 14, 2023	MODERATE	MEDIUM	CLOSED	December 8, 2023	7.2.1
243	Remove Make File Warning Messages During Compilations	Graham Kus, MathWorks; Michael Schaefer, Zuken; Curtis Clark, Ansys; Bob Ross, Teraspeed Labs	May 30, 2023	ANNOYING	LOW	CLOSED	December 8, 2023	7.2.1
242	Change Caution to Error for Illegal NC as signal_type and Change Message	Randy Wolff, Siemens	May 28, 2023	SEVERE	MEDIUM	CLOSED	December 8, 2023	7.2.1
241	Remove or Revise EMD Warning for Legal signal_name, signal_type Combinations	Randy Wolff, Siemens	May 26, 2023	SEVERE	MEDIUM	CLOSED	December 8, 2023	7.2.1
240	Parser Crashes When [Interconnect Model Group] Name is Missing	Arpad Muranyi, Siemens EDA	March 3, 2023	SEVERE	HIGH	CLOSED	April 21, 2023	7.2.0



TSCHK Development

TSCHK Parser Issue Reports (BUGs)

ID#	Title	Requester	Date Submitted	Severity	Priority	Status	Date Closed
6	TSCHK2 Parser Security Improvements	Michael Mirmak	September 19, 2022	MODERATE	MEDIUM	CLOSED	April 19, 2024
5	Code Change for Faster File Reading	Michael Schaefer, Zuken	June 20, 2022	ENHANCEMENT	LOW	CLOSED	April 19, 2024
4	Same [Reference] Values Permitted when Converting to Touchstone 1	Randy Wolff, Micron Technology	January 15, 2021	ENHANCEMENT	LOW	CLOSED	August 12, 2021
3	Canonical Mode Adds Spaces, Significantly Increases File Size	Michael Mirmak, Intel Corporation	March 20, 2014	ENHANCEMENT	LOW	CLOSED	August 12, 2021
2	Crash With Illegal Mixed-Mode Data Combinations	Arpad Muranyi and Vladimir Dmitriev-Zdorov, Mentor Graphics Corp.	Sept. 18, 2012	SEVERE	MEDIUM	CLOSED	August 12, 2021
1	Vague Option Error Message	Michael Mirmak, Intel Corp.	October 7, 2011	ANNOYING	LOW	CLOSED	August 12, 2021

- The latest parser 2.1.0 was delivered on April 19, 2024
- Covers 2 BUG fixes (BUG 5 and BUG 6)
 - <https://ibis.org/bugs/tschk/>
- TSCHK3 is under planning process for 2025

Recent and Future Developments in IBIS?



- IBIS Open Forum’s task groups are discussing these topics:
 - Expanded system-level perspective
 - Clock/data relationships, timing information, equalization training
 - Power Integrity focused modeling
 - PSIJ related BIRD220.2
 - SPIM for transient analysis
 - Voltage regulator, diode, and inductor models
 - Multi-level analog buffer modeling
 - Interconnect Modeling
 - Finalize Touchstone 3.0, including size reduction (pole-residue support), port mapping, and referencing documentation
 - Updates to IBIS Interconnect and EMD for Touchstone 3.0, including new referencing types and port maps
 - Expansion of IBIS-ISS to cover W-element “wrappers” for Touchstone data
 - Quality and Testing
 - IBISCHK8 parser development
 - Specification Clarification
 - Adding a Definitions Section to IBIS (BIRD230.1 accepted on May 31, 2024)
 - Clarifications on AMI Block Concepts (BIRD231 accepted on May 31, 2024)
 - More clarifications might come from Editorial Task Group for IBIS 8.0
- What else should we be looking at? Bring your ideas!

Participation in IBIS



- The success of IBIS depends on active participation and volunteering
- Bringing your ideas and talents to IBIS
 - Task groups for technical discussions and document editing
 - IBIS email reflectors
 - Open Forum teleconferences for event planning and voting
 - Summit presentations
 - IBIS Board and task group volunteering
 - Writing BIRDs – Buffer Issue Resolution Documents
 - Official method for submitting a proposed change to the IBIS specification
 - Many developed collaboratively in task groups
 - Discussed and voted on in Open Forum meetings



IBIS Website Resources



IBIS Summits →

Task Group Info →

Member FAQ →

Spec documents →

*IRDs →

Email support →

Syntax Parser Downloads →

The screenshot shows the IBIS Open Forum website. At the top, it says "Welcome to the IBIS Open Forum". Below this, there are two "NEW" announcements: "TSCHK2.1.0 parser is released and available for free executable download" and "Touchstone 2.1 Specification is approved and available for download". The main content is divided into three sections: "Our Specifications", "Our Members", and a footer. "Our Specifications" lists: I/O Buffer Information Specification (IBIS 7.2), IBIS Interconnect Modeling Specification (ICM 1.1), IBIS Interconnect SPICE Subcircuit Specification (IBIS-ISS 1.0), and Touchstone® File Format Specification (Touchstone 2.1). "Our Members" displays a grid of logos for various companies including Altair, AMD, Analog Devices, Ansys, Applied Simulation Technology, Aurora System, Broadcom, Cadence, Celestica, Cisco, Dassault Systemes, GE HealthCare, Google, Huawei, Infineon, Intel, Keysight, Marvell, MathWorks, Micron, Missouri S&T, SI-Clarity, Siemens, Signal Edge Solutions, ST, Synopsys, ZTE, and Zuken. The footer contains a paragraph about the IBIS Open Forum's role in managing specifications and standards, and provides contact information for the Open Forum Chair or IBIS Officers.

IBIS.org

[Thank You]



An SAE Industry Technologies Consortia Program

IBIS Open Forum:

Web: <https://ibis.org>

Email: info@ibis.org

We welcome participation
by all IBIS model makers,
EDA tool vendors, IBIS model
users, and interested parties.